

XENSIV™ integrated hall ICs for linear and off-axis rotary motion detection

Key benefits and features

The benefits and features of this device are listed below:

Table 1 Added value of using AS5304/AS5306

Benefits	Features
Contactless motion and position sensing	Highest reliability and durability in harsh environments
High speed measurement	Control of high speed movements
Robust against external magnetic stray fields	Lower material cost (no magnetic shielding needed)

- High speed, up to 20 m/s (AS5304), 12 m/s (AS5306)
- Magnetic pole pair length: 4 mm (AS5304) or 2.4 mm (AS5306)
- Resolution: 25 μm (AS5304) or 15 μm (AS5306)
- 40 pulses/160 positions per magnetic period
- 1 index pulse per pole pair
- Linear movement measurement using multi-pole magnetic strips
- Circular off-axis movement measurement using multi-pole magnetic rings
- 4.5 V to 5.5 V operating voltage
- Magnetic field strength indicator, magnetic field alarm for end-of-strip or missing magnet

Applications

The AS5304 and AS5306 are ideal for high speed linear motion and off-axis rotation measurement in applications, such as electrical motors, X-Y-stages, rotation knobs, and industrial drives.

General description

The AS5304/AS5306 are single-chip ICs with integrated Hall elements for measuring linear or rotary motion using multi-pole magnetic strips or rings. This allows the usage of the AS5304/AS5306 in applications where the Sensor IC cannot be mounted at the end of a rotating device (e.g. at hollow shafts). Instead, the AS5304/AS5306 are mounted off-axis underneath a multi-pole magnetized ring or strip and provides a quadrature incremental output with 40 pulses per pole period at speeds of up to 20 meters/second (AS5304) or 12 meters/second (AS5306).

A single index pulse is generated once for every pole pair at the Index output. Using, for example, a 32 pole-pair magnetic ring, the AS5304/AS5306 can provide a resolution of 1280 pulses/revolution, which is equivalent to 5120 positions/revolution or 12.3 bit. The maximum speed at this configuration is 9375 rpm.

The pole pair length is 4 mm (2 mm north pole/2 mm south pole) for the AS5304, and 2.4 mm (1.2 mm north pole/1.2 mm south pole) for the AS5306. The chip accepts a magnetic field strength down to 5 mT (peak). Both chips are available with push-pull outputs (AS5304A) or with open drain outputs (AS530xB). The AS5304/AS5306 are available in a small 20-pin TSSOP package and specified for an operating ambient temperature of -40°C to 125°C.

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1 Block diagram

The functional blocks of the AS5304 and AS5306 are shown below:

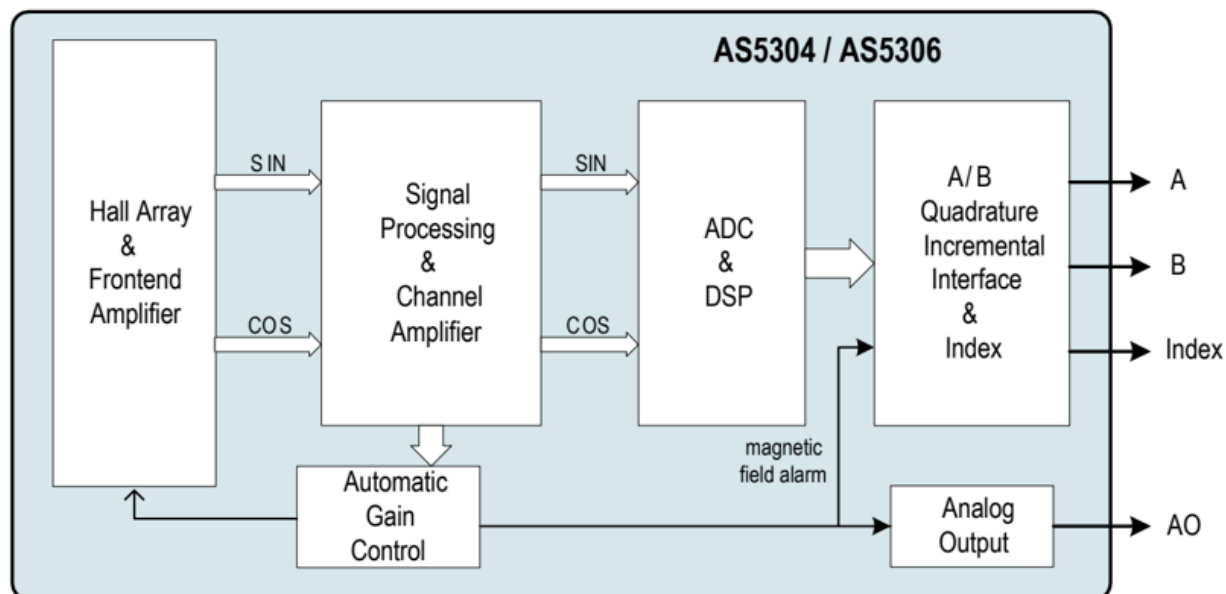


Figure 1 Functional blocks of the AS5304/06

2 Pin assignments

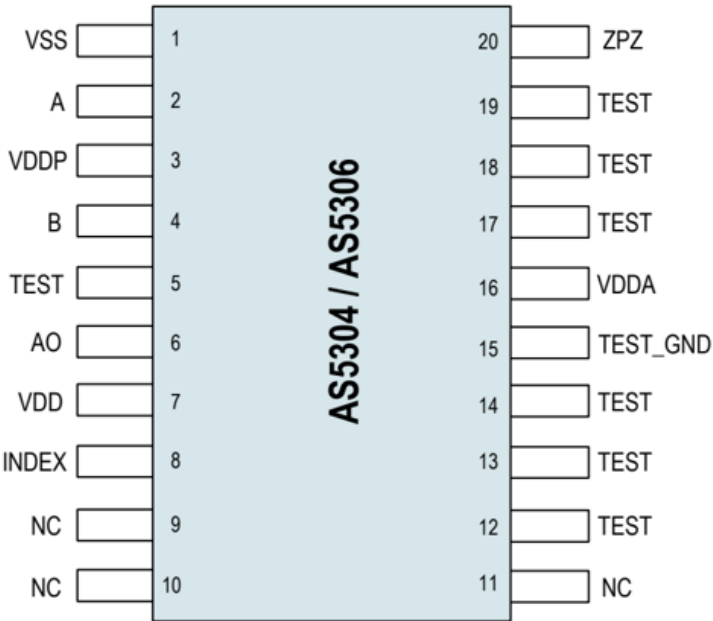


Figure 2 Pin assignments (Top view)

Table 2 Pin description

Pin number	Pin name	Pin type	Description
1	VSS	Supply pin	Supply ground
2	A	Digital output push pull or open drain (programmable)	Incremental quadrature position output A. Short circuit current limitation
3	VDDP	Supply pin	Peripheral supply pin, connect to VDD
4	B	Digital output push pull or open drain (programmable)	Incremental quadrature position output B. Short Circuit Current Limitation
5,12,13,14,17,18,19	TEST	Analog input/output	Test pins, must be left open
6	AO	Analog output	AGC Analog Output. (Used to detect low magnetic field strength)
7	VDD	Supply pin	Positive supply pin
8	Index	Digital output push pull or open drain (programmable)	Index output, active HIGH. Short Circuit Current Limitation

(table continues...)

Table 2 (continued) Pin description

Pin number	Pin name	Pin type	Description
9, 10, 11	TEST	Analog input/output	Test pins, must be left open
15	TEST_GND	Supply pin	Test pin, must be connected to VSS
16	VDDA Hall		Hall Bias Supply Support (connected to VDD)
20	ZPZmskdis	Digital input	Test input, connect to VSS during operation

3 Absolute maximum ratings

Stresses beyond those listed under [Absolute maximum ratings](#) may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under [Electrical characteristics](#) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 3 Absolute maximum ratings

Symbol	Parameter	Min.	Max.	Units	Comments
VDD	Supply	-0.3	7	V	
V _{in}	Input pin voltage	VSS-0.5	VDD+0.5	V	
I _{scr}	Input current (latchup immunity)	-100	100	mA	JESD78
ESD _{HBM}	Electrostatic discharge (human body model)	±2		kV	MIL 883 E method 3015
Θ _{JA}	Package thermal resistance		114.5	°C/W	Still Air/Single Layer PCB
T _{strg}	Storage temperature	-55	150	°C	
T _{body}	Soldering conditions		260	°C	IPC/JEDEC J-STD-020
RH _{NC}	Relative Humidity non-condensing	5	85	%	
MSL	Moisture Sensitivity Level	3			Represents a maximum floor life time of 168h

4 Electrical characteristics

All limits are guaranteed. The parameters with min and max values are guaranteed with production tests or SQC (Statistical Quality Control) methods.

4.1 Operating conditions

Table 4 Operating conditions

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
AVDD	Positive supply voltage		4.5	5.0	5.5	V
DVDD	Digital supply voltage					
VSS	Negative supply voltage		0.0	0.0	0.0	V
IDD	Power supply current, AS5304	A/B/Index, AO unloaded!	25		35	mA
	Power supply current, AS5306		20		30	
T _{amb}	Ambient temperature		-40		125	°C
T _J	Junction temperature		-40		150	°C
LSB	Resolution	AS5304		25		μm
		AS5306		15		
INL	Integral nonlinearity	Ideal input signal (ErrMax - ErrMin) / 2			2.5	LSB
DNL	Differential nonlinearity	No missing pulses. Optimum alignment			±0.5	LSB
Hyst	Hysteresis		1	1.5	2	LSB

4.2 System parameters

Table 5 System parameters

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
T _{PwrUp}	Power up time	Amplitude within valid range/ Interpolator locked, A B Index enabled			500	μs
T _{Prop}	Propagation delay	Time between change of input signal to output signal			20	μs

4.3 A/B/C Push/Pull or Open drain output

Push Pull Mode is set for AS5304A, Open Drain Mode is set for AS530xB versions.

Table 6 Open drain output

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
V_{OH}	High level output voltage	Push/Pull mode	0.8 VDD			V
V_{OL}	Low level output voltage				0.4 + VSS	V
I_{LOH}	Current source capability	Push/Pull mode	12	14		mA
I_{LOL}	Current sink capability		13	15		mA
I_{Short}	Short circuit limitation current	Reduces maximum operating temperature		25	39	mA
C_L	Capacitive load	see Figure 3		20		pF
R_L	Load resistance	see Figure 3		820		Ω
t_R	Rise time	Push/Pull mode			1.2	μs
t_F	Fall time				1.2	μs

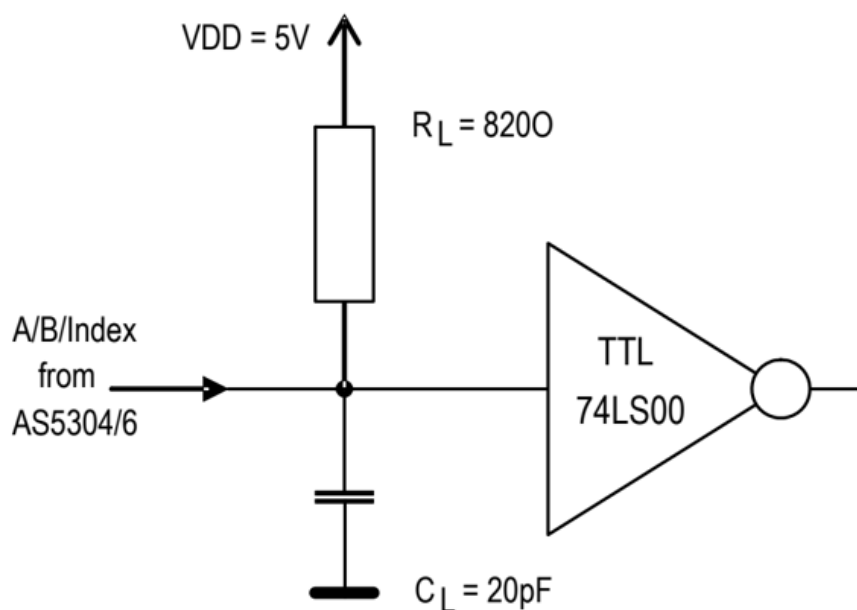


Figure 3 Typical digital load

4.4 CAO analog output buffer

Table 7 CAO analog output buffer

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
V_{OutRange}	Minimum output voltage	Strong field, minimum AGC	0.5	1	1.2	V
V_{OutRange}	Maximum output voltage	Weak field, maximum AGC	3	4	5.1	V
V_{Offs}	Offset				±10	mV
I_{L}	Current sink/source capability		5			mA
I_{Short}	Average short circuit current	Reduces maximum operating temperature	6		40	mA
C_{L}	Capacitive load			10		pF
BW	Bandwidth			5		kHz

4.5 Magnetic input

Table 8 Magnetic input

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
$L_{\text{P_FP}}$	Magnetic pole length	AS5304		2.0		mm
		AS5306		1.2		
T_{FP}	Magnetic pole pair length	AS5304		4.0		mm
		AS5306		2.4		
A_{mag}	Magnetic amplitude		10		60	mT
	Operating dynamic input range		1:6		1:12	
Off_{mag}	Magnetic offset				±0.5	mT
T_{dmag}	Magnetic temperature drift				-0.2	%/K
f_{mag}	Input frequency		0		5	kHz

5 Detailed description

The AS5304/AS5306 require a multi-pole magnetic strip or ring with a pole length of 2 mm (4 mm pole pair length) on the AS5304, and a pole length of 1.2 mm (2.4 mm pole pair length) on the AS5306. The magnetic field strength of the multi-pole magnet should be in the range of 5 mT to 60 mT at the chip surface.

The Hall elements on the AS5304/AS5306 are arranged in a linear array.

By moving the multi-pole magnet over the Hall array, a sinusoidal signal (SIN) is generated internally. With proper configuration of the Hall elements, a second 90° phase shifted sinusoidal signal (COS) is obtained. Using an interpolation circuit, the length of a pole pair is divided into 160 positions and further decoded into 40 quadrature pulses.

An Automatic Gain Control provides a large dynamic input range of the magnetic field.

An Analog output pin (AO) provides an analog voltage that changes with the strength of the magnetic field (see [The AO output](#)).

5.1 Electrical connection

The supply pins VDD, VDDP and VDDA are connected to +5V. Pins VSS and TEST_GND are connected to the supply ground. A 100 nF decoupling capacitor close to the device is recommended.

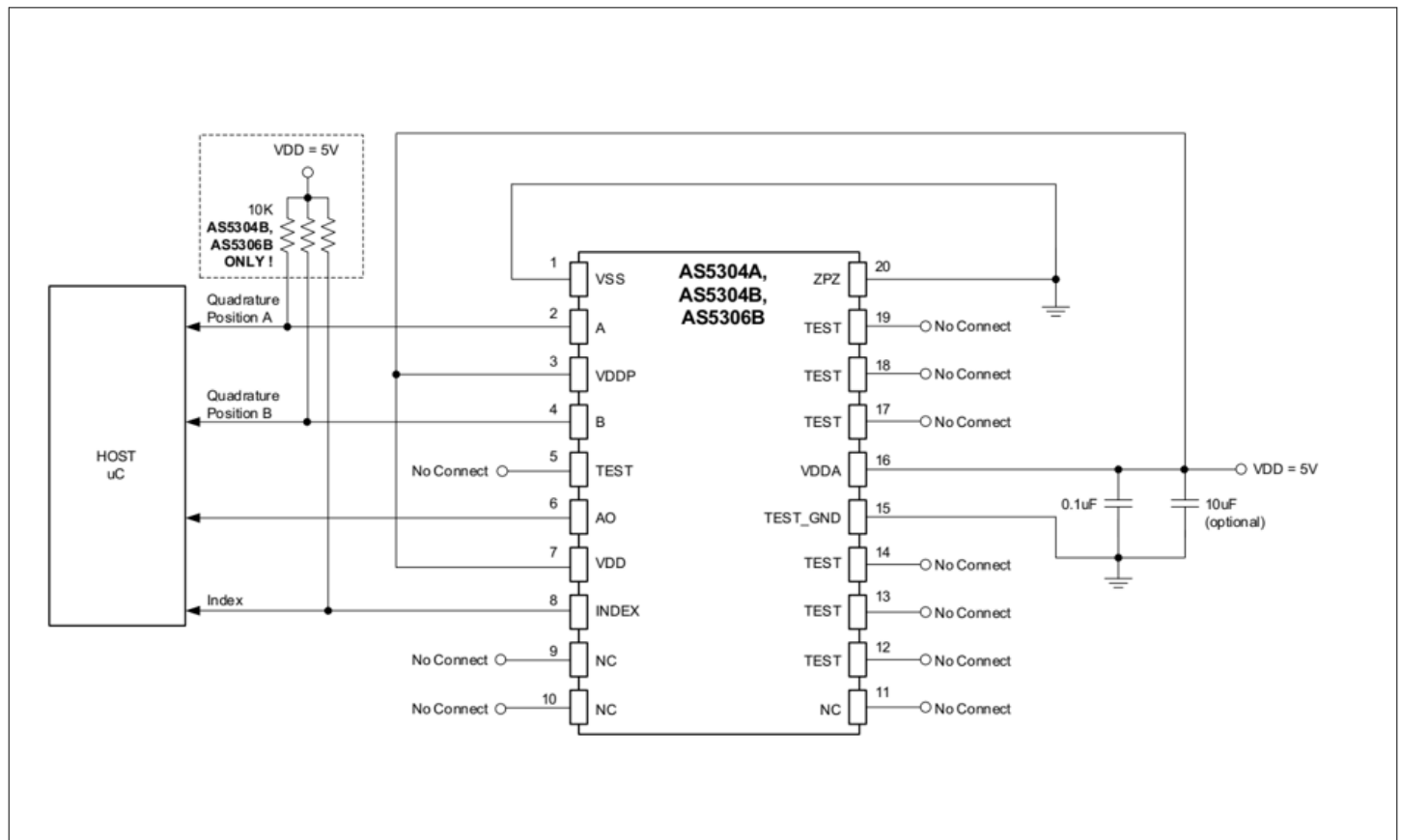


Figure 4 Electrical connection of the AS5304/AS5306

5.2 Incremental quadrature AB output

The digital output is compatible to optical incremental encoder outputs. Direction of rotation is encoded into two signals A and B that are phase-shifted by 90°. Depending on the direction of rotation, A leads B (CW) or B leads A (CCW).

5.2.1 Index pulse

A single index pulse is generated once for every pole pair. One pole pair is interpolated to 40 quadrature pulses (160 steps), so one index pulse is generated after every 40 quadrature pulses (see [Figure 5](#)).

The Index output is switched to Index = high, when a magnet is placed over the Hall array as shown in [Figure 6](#), top graph: the north pole of the magnet is placed over the left side of the IC (top view, pin#1 at bottom left) and the south pole is placed over the right side of the IC.

The index output will switch back to Index = low, when the magnet is moved by one LSB from position $X=0$ to $X=X1$, as shown in [Figure 6](#), bottom graph. One LSB is 25 μm for AS5304 and 15 μm for AS5306.

Note: *Since the small step size of 1 LSB is hardly recognizable in a correctly scaled graph it is shown as an exaggerated step in the bottom graph of [Figure 6](#).*

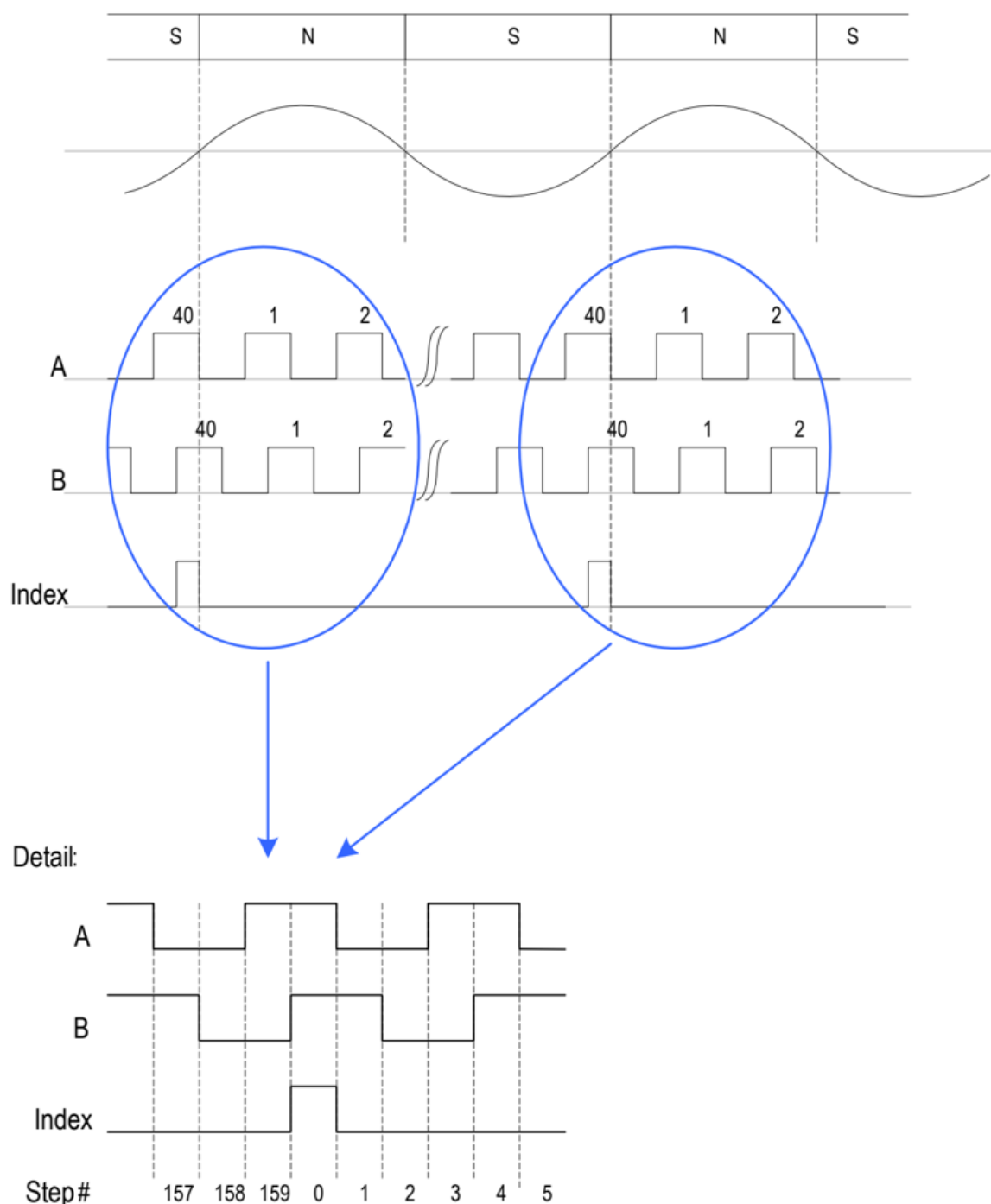


Figure 5 Quadrature A/B and index output

5.2.2 Magnetic field warning indicator

The AS5304 can also provide a low magnetic field warning to indicate a missing magnet or when the end of the magnetic strip has been reached. This condition is indicated by using a combination of A, B and Index, that does not occur in normal operation:

A low magnetic field is indicated with:

Index = high

A=B=low

5.2.3 Vertical distance between magnet and IC

The recommended vertical distance between magnet and IC depends on the strength of the magnet and the length of the magnetic pole.

Typically, the vertical distance between magnet and chip surface should not exceed $\frac{1}{2}$ of the pole length. That means for AS5304, having a pole length of 2.0 mm, the maximum vertical gap should be 1.0 mm. For the AS5306, having a pole length of 1.2 mm, the maximum vertical gap should be 0.6 mm. These figures refer to the chip surface. Given a typical distance of 0.2 mm between chip surface and IC package surface, the recommended vertical distances between magnet and IC surface are therefore:

AS5304: ≤ 0.8 mm

AS5306: ≤ 0.4 mm

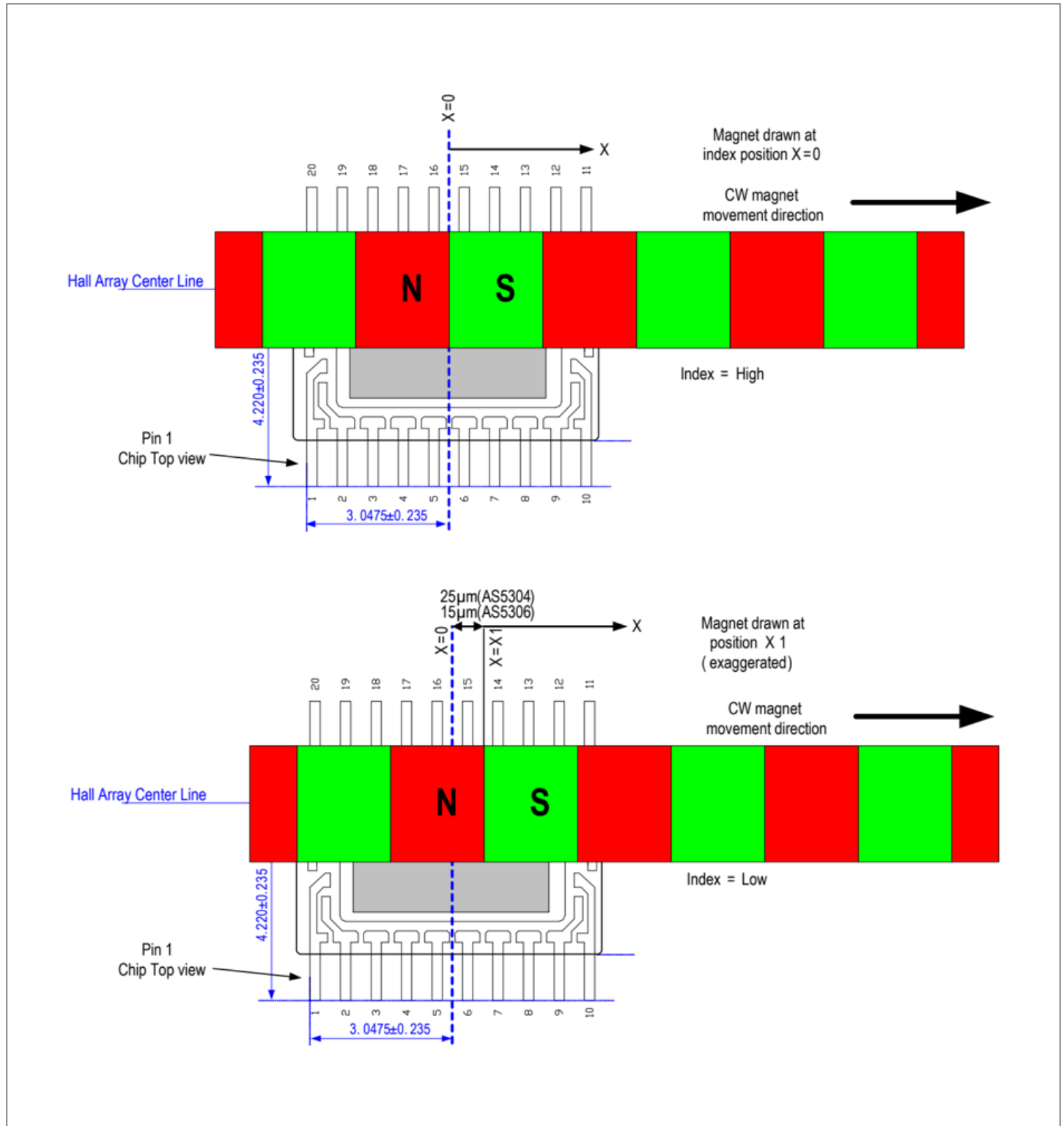


Figure 6 Magnet placement for index pulse generation

5.2.4 Soft stop feature for linear movement measurement

When using long multi-pole strips, it may often be necessary to start from a defined home (or zero) position and obtain absolute position information by counting the steps from the defined home position. The AS5304/AS5306 provide a soft stop feature that eliminates the need for a separate electro-mechanical home position switch or an optical light barrier switch to indicate the home position.

The magnetic field warning indicator (see [Magnetic field warning indicator](#)) together with the index pulse can be used to indicate a unique home position on a magnetic strip:

1. Firstly, the AS5304/AS5306 move to the end of the strip until a magnetic field warning is displayed (Index = high, A=B=low).
2. Then, the AS5304/AS5306 move back towards the strip until the first index position is reached (Note that an index position is generated once for every pole pair, it is indicated with: Index = high, A=B= high). Depending on the polarity of the strip magnet, the first index position may be generated when the end of the magnet strip only covers one half of the Hall array. This position is not recommended as a defined home position, as the accuracy of the AS5304/AS5306 are reduced as long as the multi-pole strip does not fully cover the Hall array.
3. It is therefore recommended to continue to the next (second) index position from the end of the strip (Index = high, A=B= high). This position can now be used as a defined home position.

5.3 Incremental hysteresis

If the magnet is sitting right at the transition point between two steps, the noise in the system may cause the incremental outputs to jitter back and forth between these two steps, especially when the magnetic field is weak.

To avoid this unwanted jitter, a hysteresis has been implemented. The hysteresis lies between 1 and 2 LSB, depending on device scattering. [Figure 7](#) shows an example of 1 LSB hysteresis: the horizontal axis is the lateral position of the magnet as it scans across the IC, the vertical axis is the change of the incremental outputs, as they step forward (blue line) with movement in +X direction and backward (red line) in -X direction.

Note: $1\text{LSB} = 25\text{ }\mu\text{m}$ for AS5304, $15\text{ }\mu\text{m}$ for AS5306.

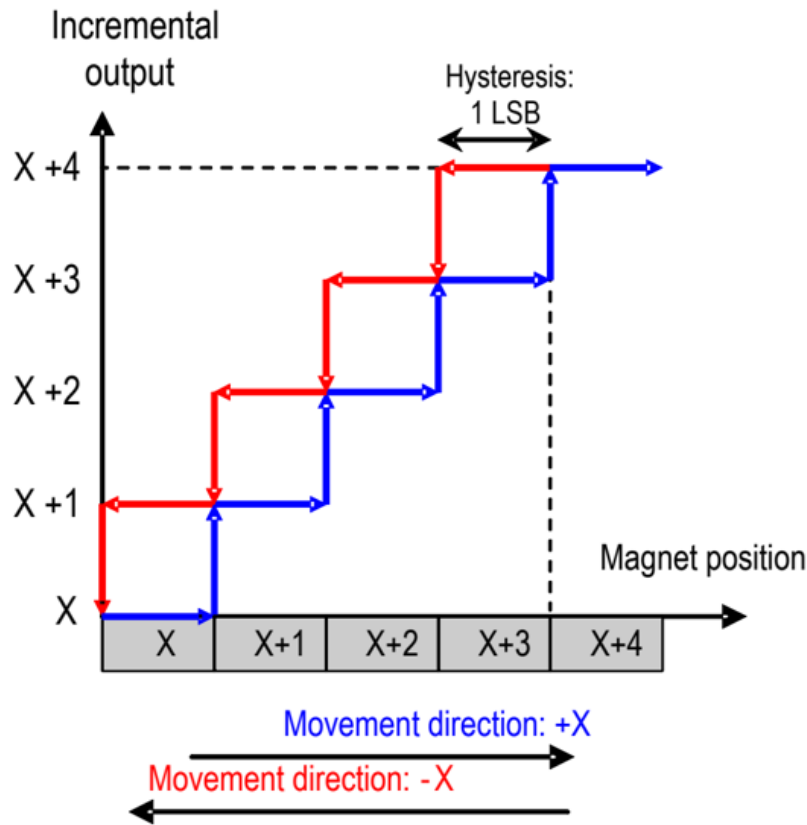


Figure 7 Hysteresis of the incremental output

5.4 Integral non-linearity (INL)

The INL (integral non-linearity) is the deviation between indicated position and actual position. It is better than 1 LSB for both AS5304 and AS5306, assuming an ideal magnet. Pole length variations and imperfections of the magnet material, which lead to a non-sinusoidal magnetic field will attribute to additional linearity errors.

5.4.1 Error caused by pole length variations

Figure 8 and Figure 9 show the error caused by a non-ideal pole length of the multi-pole strip or ring. This is less of an issue with strip magnets, as they can be manufactured exactly to specification using the proper magnetization tooling.

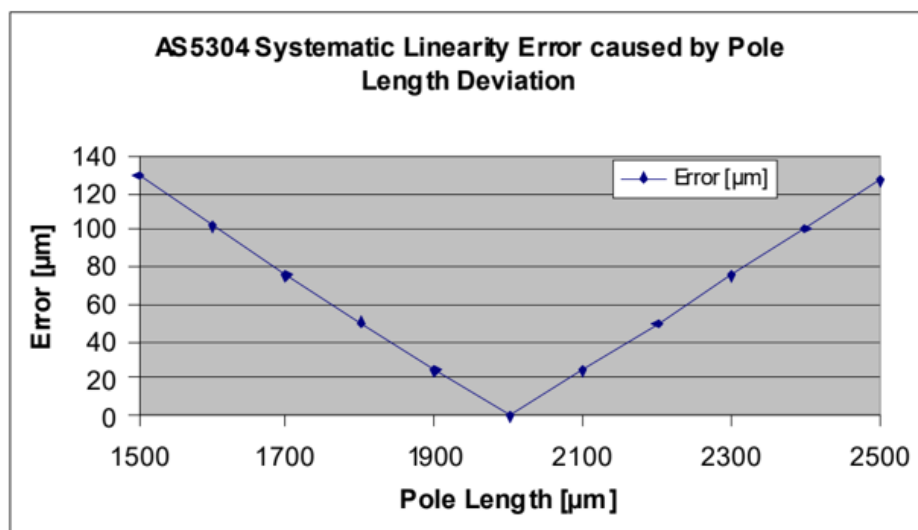


Figure 8 Additional error caused by pole length variation: AS5304

However, when using a ring magnet (see [Figure 12](#)), the pole length differs depending on the measurement radius. For optimum performance, it is therefore essential to mount the IC such that the Hall sensors are exactly underneath the magnet at the radius where the pole length is 2.0 mm (AS5304) or 1.2 mm (AS5306), see also [Multi-pole ring diameter](#).

Note: This is an additional error, which must be added to the intrinsic errors [Integral non-linearity \(INL\)](#) and [Dynamic non-linearity \(DNL\)](#).

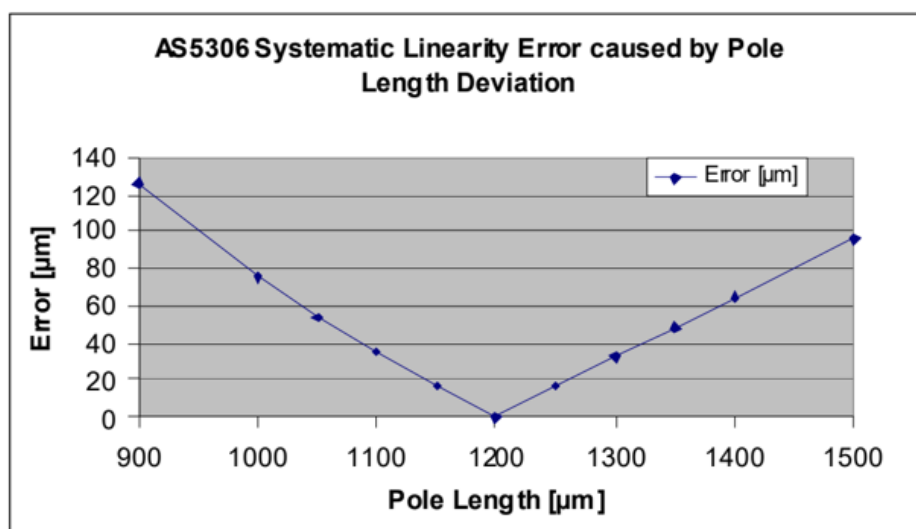


Figure 9 Additional error caused by pole length variation: AS5306

5.5 Dynamic non-linearity (DNL)

The DNL (dynamic non-linearity) describes the non-linearity of the incremental outputs from one step to the next. In an ideal system, every change of the incremental outputs would occur after exactly one LSB (e.g. 25 μm on AS5304). In practice however, this step size is not ideal, the output state will change after $1 \text{ LSB} \pm \text{DNL}$. The DNL must be $< \pm \frac{1}{2} \text{ LSB}$ to avoid a missing code. Consequently, the incremental outputs will change when the magnet movement over the IC is minimum 0.5 LSB and maximum 1.5 LSBs.

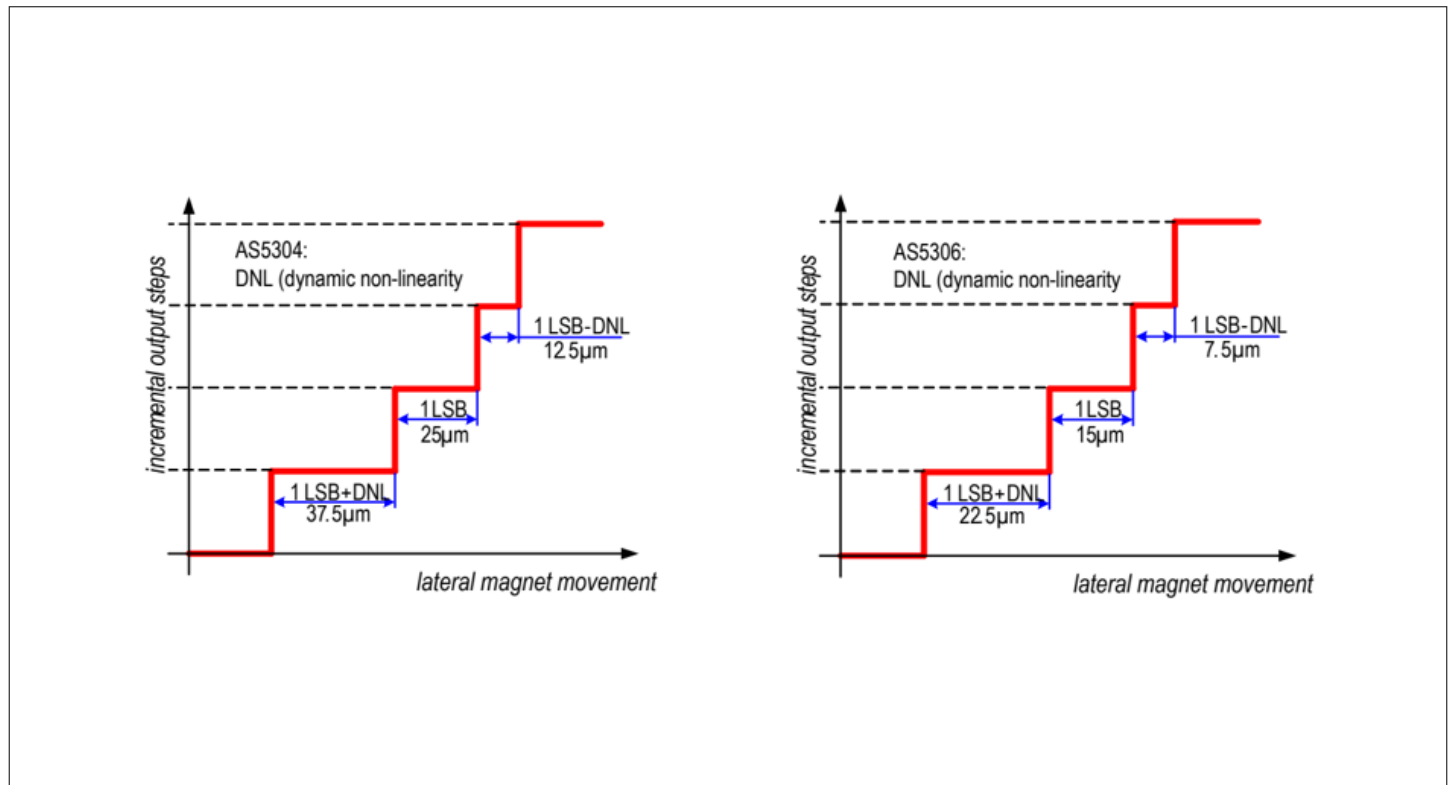


Figure 10 DNL of AS5304 (left) and AS5306 (right)

5.6 The AO output

The Analog Output (AO) provides an analog output voltage that represents the Automatic Gain Control (AGC) of the Hall sensors signal control loop.

This voltage can be used to monitor the magnetic field strength and hence the gap between magnet and chip surface:

- Short distance between magnet and IC -> strong magnetic field -> low loop gain -> low AO voltage
- Long distance between magnet and IC -> weak magnetic field -> high loop gain -> high AO voltage

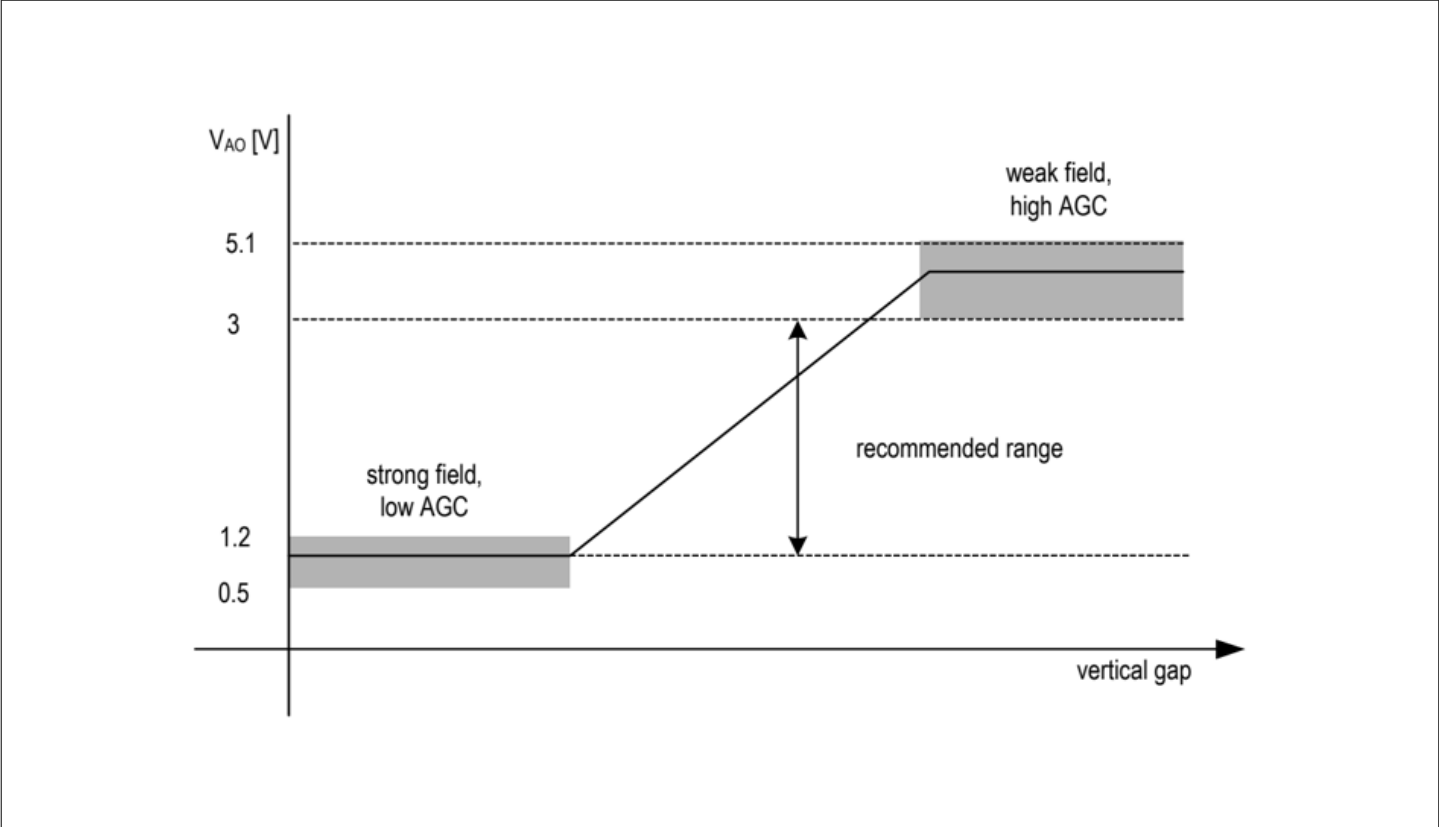


Figure 11 AO vs. AGC, magnetic field strength, magnet-to-IC gap

6 Application information



Figure 12 AS5304 (AS5306) with multi-pole ring magnet

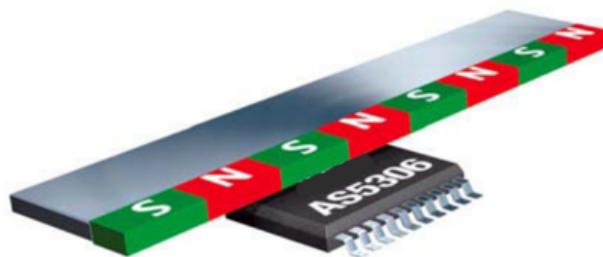


Figure 13 AS5306 (AS5304) with magnetic multi-pole strip magnet for linear motion measurement

6.1 Resolution and maximum rotating speed

When using the AS5304/AS5306 in an off-axis rotary application, a multi-pole ring magnet must be used. Resolution, diameter and maximum speed depend on the number of pole pairs on the ring.

6.1.1 Resolution

The angular resolution increases linearly with the number of pole pairs. One pole pair has a resolution (= interpolation factor) of 160 steps or 40 quadrature pulses.

Resolution [steps] = [interpolation factor] x [number of pole pairs]

Resolution [bit] = $\log(\text{resolution[steps]}) / \log(2)$

Example: Multi-pole ring with 22 pole pairs

Resolution = $160 \times 22 = 3520$ steps per revolution

= $40 \times 22 = 880$ quadrature pulses/revolution

= 11.78 bits per revolution = 0.1023° per step

6.1.2 Multi-pole ring diameter

The length of a pole pair across the median of the multi-pole ring must remain fixed at either 4 mm (AS5304) or 2.4 mm (AS5306). Hence, with increasing pole pair count, the diameter increases linearly with the number of pole pairs on the magnetic ring.

Magnetic ring diameter = [pole length] * [number of pole pairs] / π

for AS5304: $d = 4.0 \text{ mm} * \text{number of pole pairs} / \pi$

for AS5306: $d = 2.4 \text{ mm} * \text{number of pole pairs} / \pi$

Example: (same as above) Multi-pole ring with 22 pole pairs for AS5304

Ring diameter = $4 * 22 / 3.14 = 28.01 \text{ mm}$ (this number represents the median diameter of the ring, this is where the Hall elements of the AS5304/AS5306 should be placed; (see [Figure 16](#)).

For the AS5306, the same ring would have a diameter of: $2.4 * 22 / 3.14 = 16.8 \text{ mm}$

6.1.3 Maximum rotation speed

The AS5304/AS5306 use a fast interpolation technique allowing an input frequency of 5 kHz. This means, it can process magnetic field changes in the order of 5000 pole pairs per second or 300000 revolutions per minute. However, since a magnetic ring consists of more than one pole pair, the above value must be divided by the number of pole pairs to get the maximum rotation speed:

Maximum rotation speed = $300000 \text{ rpm} / [\text{number of pole pairs}]$

Example: (same as above) Multi-pole ring with 22 pole pairs: Maximum speed = $300000 / 22 = 13636 \text{ rpm}$ (this is independent of the pole length)

6.1.4 Maximum linear travelling speed

For linear motion sensing, a multi-pole strip using equally spaced north and south poles is used. The pole length is again fixed at 2.0 mm for the AS5304 and 1.2 mm for the AS5306. As shown in [Maximum rotation speed](#) above, the sensors can process up to 5000 pole pairs per second, so the maximum travelling speed is:

Maximum linear travelling speed = $5000 * [\text{pole pair length}]$

Example: Linear multi-pole strip:

Maximum linear travelling speed = $4 \text{ mm} * 5000 \text{ 1/s} = 20000 \text{ mm/s} = 20 \text{ m/s}$ {for AS5304}

Maximum linear travelling speed = $2.4 \text{ mm} * 5000 \text{ 1/s} = 12000 \text{ mm/s} = 12 \text{ m/s}$ {for AS5306}

7 Package drawings & markings

The devices are available in a 20-pin TSSOP package.

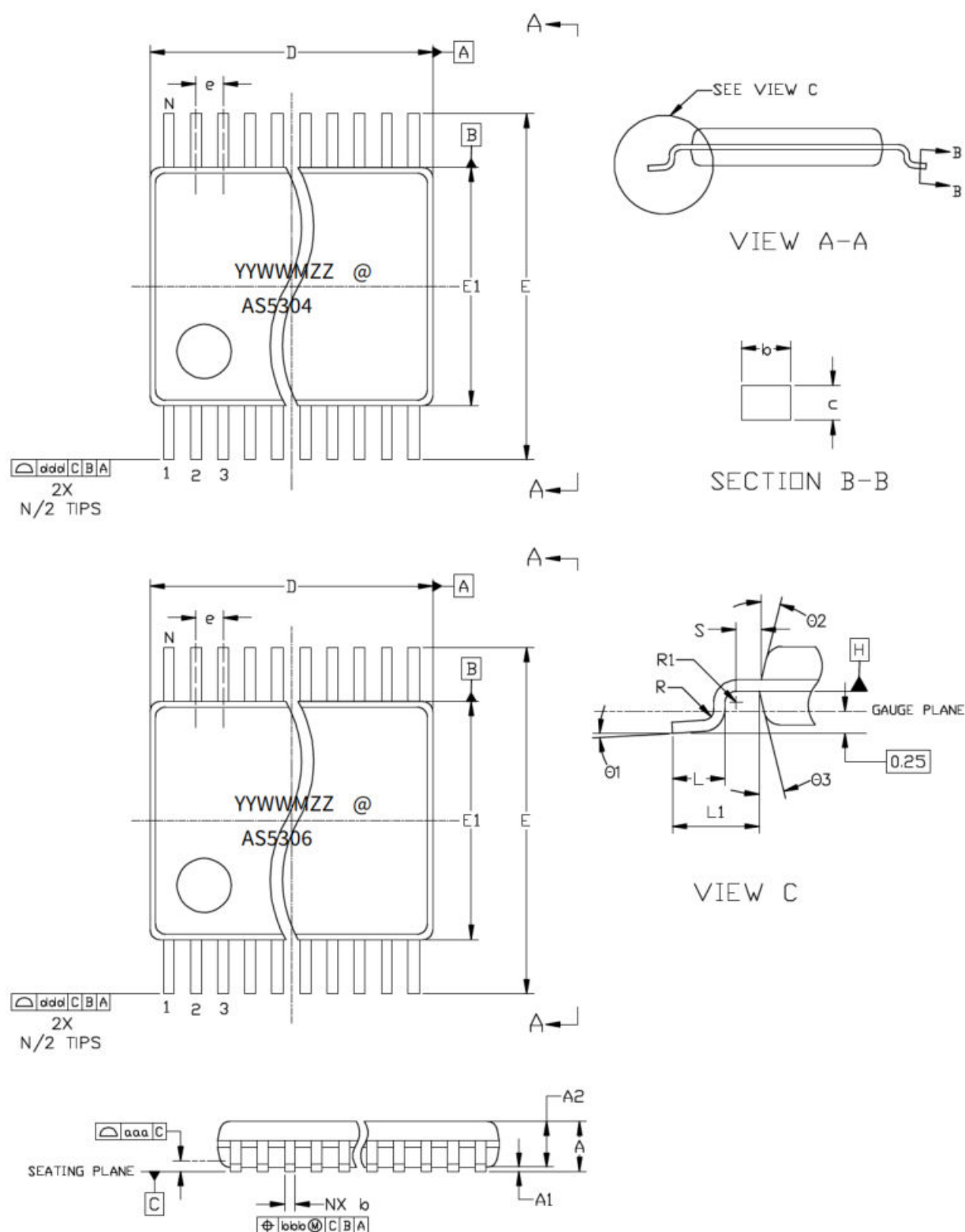


Figure 14 Packaging drawings

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	-	-	1.20	R	0.09	-	-
A1	0.05	-	0.15	R1	0.09	-	-
A2	0.80	1.00	1.05	S	0.20	-	-
b	0.19	-	0.30	q1	0°	-	8°
c	0.09	-	0.20	θ2	-	12 REF	-
D	6.40	6.50	6.60	θ3	-	12 REF	-
E	-	6.40 BSC	-	aaa	-	0.10	-
E1	4.30	4.40	4.50	bbb	-	0.10	-
e	-	0.65 BSC	-	ccc	-	0.05	-
L	0.45	0.60	0.75	ddd	-	0.20	-
L1	-	1.00 REF	-	N	20		

Figure 15 Package dimensions

Notes:

1. Dimensions and tolerancing conform to ASME Y14.5M-1994.
2. All dimensions are in millimeters. Angles are in degrees.

Table 9 Packaging code

YY	WW	M	ZZ	@
Year	Manufacturing Week	Assembly Plant Identifier	Assembly Traceability Code	Sublot Identifier

7.1 Sensor placement in package

TSSOP20/0.65 mm pin pitch

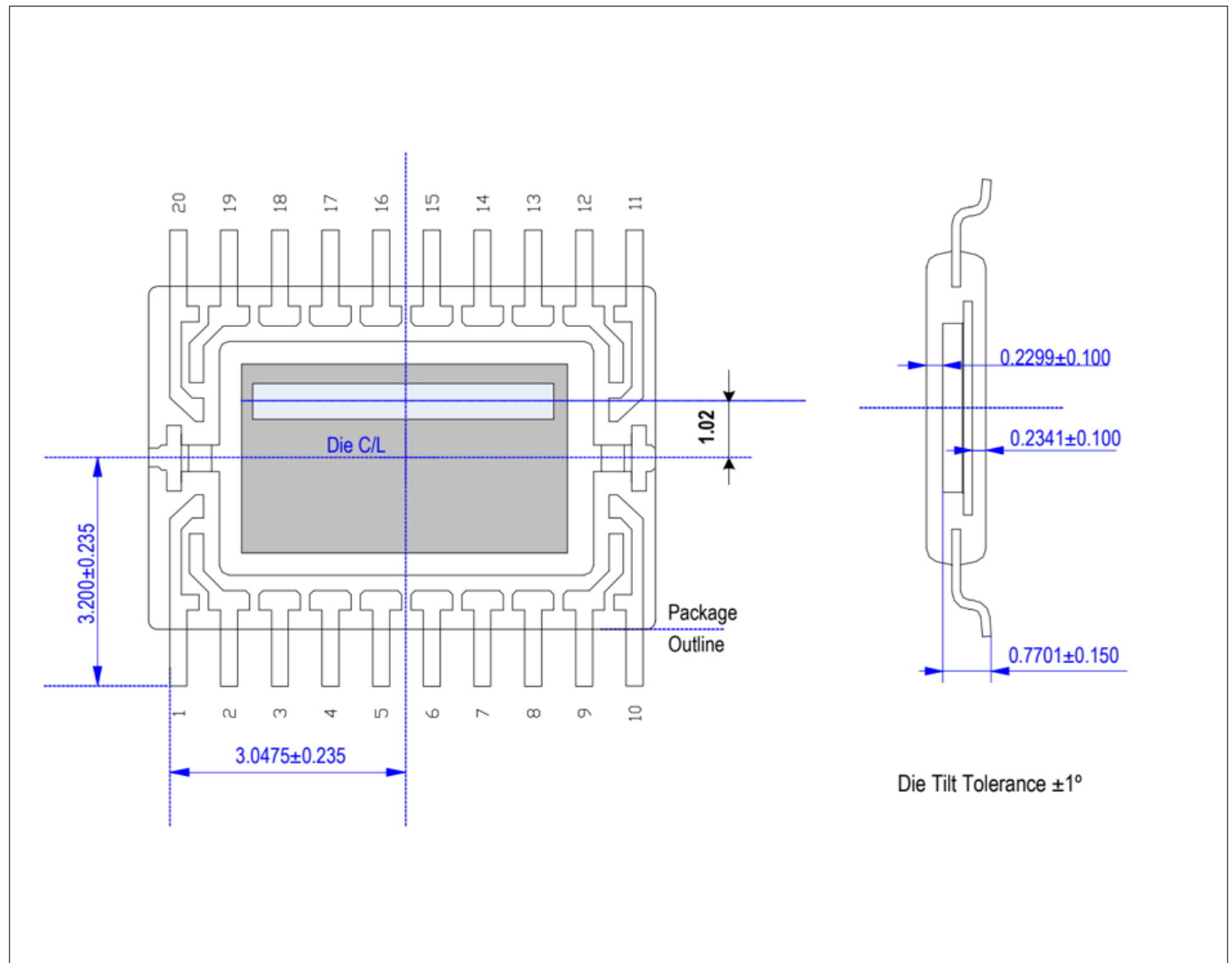


Figure 16 Sensor in package

8 Ordering information

Product type (Infineon)	Product type (ams)	Package	Description	Delivery form	Delivery quantity
AS5304					
AS5304A-TSSOP20	AS5304A	20-pin TSSOP	25 μm resolution, 2 mm Magnet pole length, Push Pull	Tape & Reel	500 pcs/ reel
AS5304A-TSSOP20-TUB-01				Tube	7400 pcs/ tube
AS5304A-TSSOP20-TUB-02					
AS5304B-TSSOP20-01	AS5304B	20-pin TSSOP	25 μm resolution, 2 mm Magnet pole length, Open Drain	Tape & Reel	500 pcs/ reel
AS5304B-TSSOP20-02					4500 pcs/ reel
AS5306					
AS5306B-TSSOP20	AS5306B	20-pin TSSOP	15 μm resolution, 1.2 mm Magnet pole length, Open Drain	Tape & Reel	4500 pcs/ reel

Revision history

Document revision	Date	Description of changes
1.00	2026-10-01	Document rebranded from ams-OSRAM to Infineon; technical specifications remain unchanged. Legacy ams changes from previous revision to revision v1-00: Initial production version

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